

FORM PTO-1449	U.S. Department of Commerce Patent and Trademark Office	Atty. Docket No. P26669	Application No. 10/524,420
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)		Applicant Reiko KAWAMURA	
		Filing Date August 19, 2003	Group Unknown

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
MM		6 9 8 4 7 4 2	01/10/06	TANIKAWA et al.			
	2005	0 2 5 0 6 7 1	11/10/05	SHIDOJI et al.			
	2006	0 0 6 3 8 3 8	03/23/06	SHIDOJI et al.			
	2006	0 0 9 4 7 8 4	05/04/06	KAGAWA et al.			
		4 7 5 7 1 4 0	07/12/88	DELUCA et al.		7/1988	
		4 3 4 6 1 0 9	08/24/82	YAMATSU et al.			
		4 9 1 7 8 2 9	04/17/90	YAMATSU et al.			
		4 9 8 8 7 3 2	01/29/91	YAMATSU et al.			
		4 8 4 1 0 3 8	06/20/89	DELUCA et al.			
		4 8 8 8 4 3 9	12/19/89	YAMATSU et al.			
		5 8 5 2 0 5 7	12/22/98	MUTO et al.			
		4 6 5 5 9 7 3	04/07/87	YAMATSU et al.			
		4 7 8 8 3 3 0	11/29/88	NAKAMOTO et al.			
		4 8 8 3 9 1 6	11/28/89	NAKAMOTO et al.			
MM		4 6 5 5 9 7 3	04/07/87	YAMATSU et al.			

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
MM	01	/ 8 0 8 5 4	11/01/01	W.I.P.O			
	56	- 1 4 0 9 4 9	11/04/81	JAPAN			
	03	/ 0 9 7 0 3 4	11/27/03	W.I.P.O			
	63	- 3 2 0 5 8	06/28/88	JAPAN			
		0 0 5 4 7 3 2	06/30/82	E.P.O			
		0 1 9 4 6 9 3	09/17/86	E.P.O			
		7 8 1 8 0 9	08/28/57	UNITED KINGDOM			
	63	- 3 4 8 5 5	07/12/88	JAPAN			
	57	- 1 0 6 6 3 8	07/02/82	JAPAN			
	2000	- 1 2 2 9 7 4	04/24/00	JAPAN			
MM	94	/ 2 2 8 1 8	10/13/94	W.I.P.O			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

MM	22	English language Abstract of JP 56-140949.
MM	23	English language Abstract of JP 57-106638.

EXAMINER	/Melenie McCormick/	DATE CONSIDERED	01/03/2007
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*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.